

ABSTRACT

A method of manufacturing semiconductor packages is proposed. A die carrier is provided having a plurality of substrate units. At least one semiconductor die is mounted on each substrate unit by an adhesive. Then the die carrier mounted with the dies is cured in a jig fixture. The jig fixture has a submold and at least one exhaust passage communicated with an external exhauster. Air in the jig fixture is drawn out by the external exhauster through the exhaust passage to form a negative-pressure environment in the jig fixture. The negative-pressure environment generates an attraction force to secure the dies to the submold and counteract thermal stresses produced in the die carrier, thereby preventing die cracking, warpage and delamination from occurrence, such that the planarity of the die carrier is assured and solder balls can be precisely secured to the die carrier in position.